

Abstract

A method of integrating an optoelectronic device, for example a vertical cavity surface emitting laser, onto the electronic substrate of a parallel optical transceiver package by positioning and maintaining the exact relative alignment of the optoelectronic device relative to the electronic substrate for application of adhesive and curing. The method includes the utilization of a multi-piece fixture which clamps the elements into position and maintains position throughout the curing process. Alternatively, the fixture can comprise a unitary assembly for clamping the elements into position and maintaining their position throughout the curing process.